

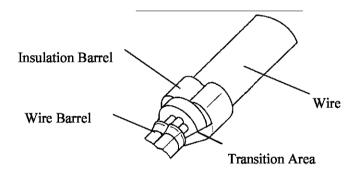
1. Scope:

This specification covers the requirements for crimping of 2.5mm pitch HPI (High Performance Interconnect Wire-To-Board System) Connector (Crimp Type) for applicator and manually operated hand tool.

2. Applicable Connectors

Contact Form	Product Part Number	Crimping Tool	Wire Size (SQmm)	Ins Diameter (mm)
Strip Terminal	440134-1	Applicator	0.08 ~ 0.30mm² (AWG #28 ~ #22)	φ 1.0 ∼ φ 1.9mm

3. Nomenclature



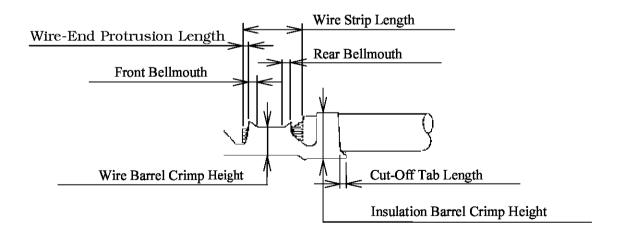


Fig.1



4 · Crimping Requirement

			Crimping R	Lequirements		
No.		Check Items	Applicator	Hand Tool	Remarks	
1	Wi	re Strip Length	1.9 ~	2.5 mm	Fig.1 —	
2	Wire-Er	nd Protrusion Length	0.3 ~	0.6 mm	Fig.1 —	
3	Cut	-Off Tab Length	0 ~ 0	0.5 mm	Fig.1 —	
4		Front	Front bellmout	h can be visible.	Fig.1 —	
	Bellmouth	Rear	0.1 ~	0.3 mm	Fig.1 —	
5	Win	re Barrel Crimp	Refer	Table.1	Fig.1 —	
6	Insulation	n Barrel Crimp Height	Refer	Refer Table.1		
7		Bend-Up	6° Max.	6° Max.		
8		Bend-Down	6° Max.	6° Max.		
9	Allowable Deviation after Crimping	Twisting	5° Max.	5° Max.		
10		Rolling	7° Max.	7° Max.		

Tool mark is allowable at crimped areas and transition areas only.

5 · Crimping Data

Table.1

		Wire	Size		Win	re Barrel	Insulation Barrel	
Contact Part	Applicator Part	Number	Size	Insulation	Crimp	Crima Usiaht	Crimp	Finished Insulation
Number	Number	of Wire	Size	Strip Length	Width	Crimp Height	Height	Diameter
		1	0.00	1.9~ 2.5mm		0.75±0.05mm		1. 0
		1	(#22) 0.22mm²	1	1.4mm	0.70±0.05mm	1.8mm	φ1.Omm ≀
440134-1	1463115-2		(#24)]	"F"		Max.	
		1	0.14mm ²			0.65±0.05mm		φ 1.9mm
		1	(#26) 0.08mm2	1		0.60~0.65mm		
			(#28)					

Table.2

Wire Size		Crimp Tensile Strength
mm ²	AWG	N (kgf) Min.
0.30	22	49.0 (5.0)
0.22	24	29.4 (3.0)
0.14	26	19.6 (2.0)
0.08	28	9.8 (1.0)

Note

- 1. Tool mark is allowable at crimped areas and transition areas only.
- 2. The dimensions of crimp width of wire barrel and insulation barrel are the dimensions of crimpting tool.

6 · Example of Applicable wire

Table.3

Wire Size	Insulation Diameter (mm)	Applicable Wire
AWG#28~22	1.0~1.9	UL-1007

All wires, including the above mentioned, need to be approved prior to usage.



AMP 2.5mm Pitch HPI High Performance Interconnect (Low Cost) Wire-To-Board System

Application Specification 114-57004 Rev. A

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